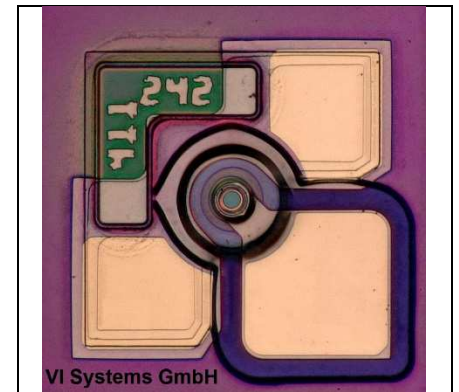


Up to 25 GBaud/s VCSEL (850nm) for high temperature applications

Product Code: V25HT-850C1 1x1 chip
 V25HT-850C4 1x4 array



VI Systems GmbH

Actual product may vary in appearance.

Preliminary

Product Description

These compact and high modulation rate high temperature top-emitting GaAs-based vertical cavity surface emitting laser (VCSEL) chips and 1xN (N=4) arrays are available as engineering samples for use in the development and evaluation of optical interconnections, optical backplanes and integrated waveguides, and next-generation optical data communications systems. The VCSELs are contacted on the top-surface individually using ground-source (GS) microprobes, wire bonds, or flip-chip bonds. This VCSEL revision characterizes with very high temperature stability and can operate from 25°C to 125°C.

Features

- Up to 4 parallel channels
- Up to 28 Gbit/s NRZ per channel
- High temperature stability
- Device-to-device pitch of 250 µm
- Suitable for wire or flip-chip bonding

Applications

- Ethernet
- Automotive applications
- Active Optical Cables (AOC)
- Short-reach 50G/100G/200G/400G Ethernet
- On-board signalling

Parameter	Typical	Notes
Emission wavelength	850 nm (available 835 – 865 nm)	
Data rate	Up to 28 Gbit/s	NRZ
Threshold current	< 0.6 mA	25-125°C
Peak output power	6 mW	

Datasheet

V25-850C-HT



Vertically Integrated Systems

Electro-optical characteristics (T = 0 to 125 °C)

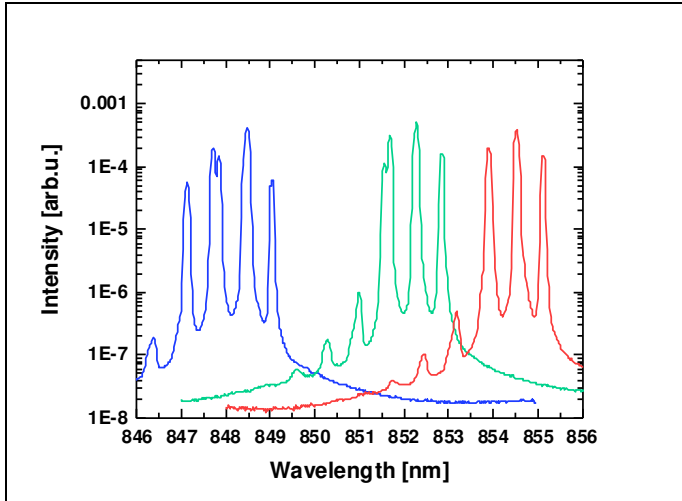
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Emission wavelength	λ		835		865	nm
Maximum data rate	BR	NRZ		28		Gbit/s
Optical bandwidth	BW (f_{3dB})	7 [mA]/25°C		18		GHz
Slope efficiency	η	25°C	0.5	0.6	0.7	W/A
		125°C		0.4		
Threshold current	I_{th}	25-125°C			0.6	mA
Differential resistance	R_d	25-125°C		100		Ω
Beam divergence	θ	FWHM		20		°
Peak output power	P_{max}	25°C	2		6	mW
		125°C	1		3	
Spectral bandwidth (RMS)	$\Delta\lambda_{RMS}$			0.5		nm
Relative Intensity Noise	RINxOMA	25°C			-130	dB/Hz
	RINxOMA	125°C			-126	dB/Hz

Absolute Maximum Ratings

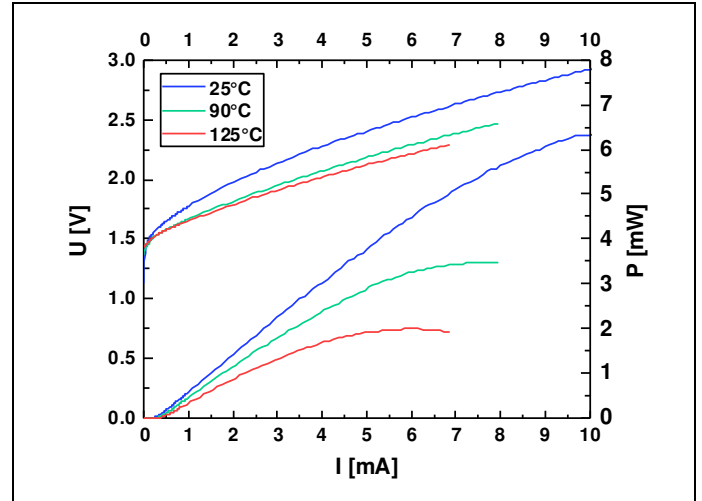
Parameter	Symbol	Test Condition	Min	Max	Unit
Peak forward current	I_f	25°C		10	mA
Maximum reverse voltage	V_{rv}			5	V
Operating temperature	T_{op}			180	°C
Storage temperature	T_{st}		-40	200	°C
Soldering temperature	T_{sl}	max 260 sec		250	°C

All product specifications and descriptions are subject to change without notice.
Please contact our sales department for additional information and to receive a quotation: sales@v-i-systems.com

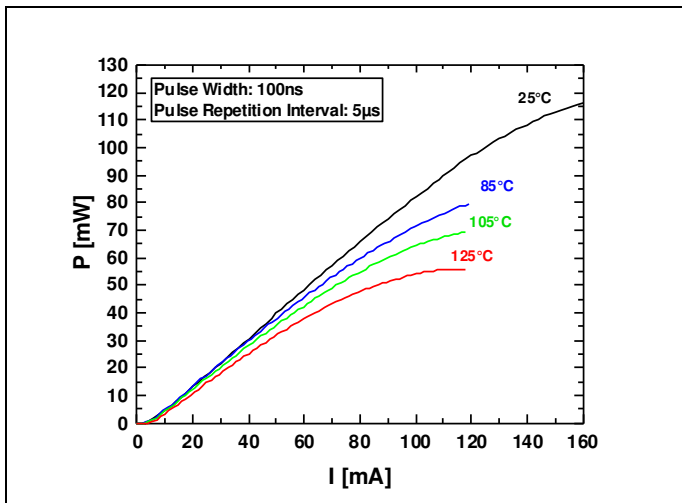
Optical spectrum



L-I-V Diagram



Pulsed L-I Diagram



Datasheet

V25-850C-HT

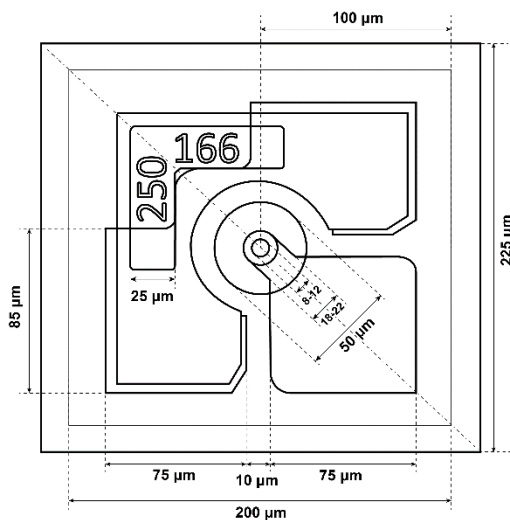


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Mechanical Dimensions

Parameter	Type	Min	Typ	Max	Unit
VCSEL pitch	All		250		μm
Length 1x1 VCSEL chip	V25HT-850C1		210	250	μm
Length 1x4 VCSEL array	V25HT-850C4		960	1000	μm
Height	All	140	150	160	μm
Width	All		210	250	μm

Dimensions



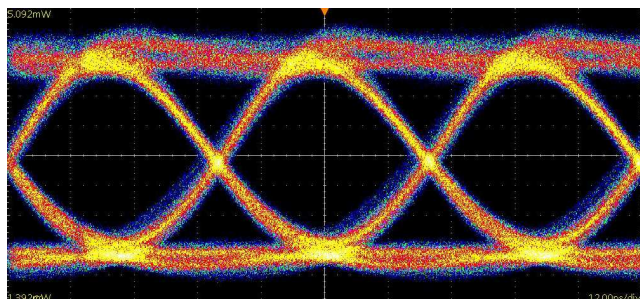
Datasheet

V25-850C-HT



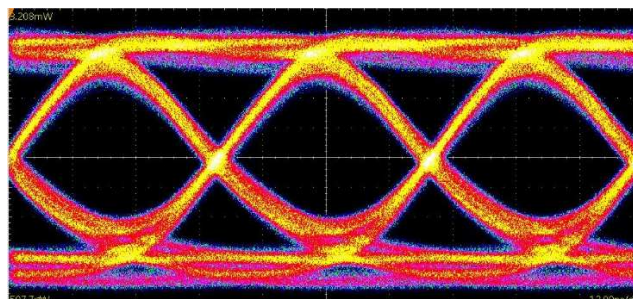
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Eye diagram at 25 Gbit/s NRZ 25°C



Receiver: Textronix 80C15-32 GHz (no DSP)

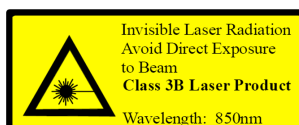
Eye diagram at 25 Gbit/s NRZ 125°C



Receiver: Textronix 80C15-32 GHz (no DSP)

Qualification Notification

The V25HT-850Cx has been tested to meet specifications outlined in this data sheet at room temperature. However, it has not undergone full qualification testing or characterization and therefore may not meet the performance specifications over all extremes.



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